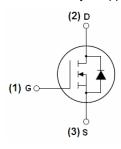
# **REASUNOS**

## N-Channel Enhancement Mode Power MOSFET

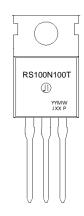


#### **Description**

The RS100N100T uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.



Schematic diagram



Marking and pin assignment

#### **General Features**

•  $V_{DS} = 100V, I_D = 100A$  $R_{DS(ON)} < 13mΩ @ V_{GS} = 10V$  (Typ:9.9mΩ)

- Special process technology for high ESD capability
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation

#### **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



TO-220 top view

#### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
RS100N100T	RS100N100T	TO-220	-	-	-

# Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>G</sub> s	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current-Continuous	100	Α
I <sub>D</sub> (100℃)	Drain Current-Continuous(TC=100°C)	80	Α
I <sub>DM</sub>	Pulsed Drain Current	380	Α
P <sub>D</sub>	Maximum Power Dissipation	200	W
	Derating factor	1.33	W/℃
E <sub>AS</sub>	Single pulse avalanche energy (Note 5)	800	mJ
$T_{J}, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 175	$^{\circ}$

#### **Thermal Characteristic**

R <sub>eJC</sub>	Thermal Resistance, Junction-to-Case (Note 2)	0.75	°C/W	
------------------	---	------	------	--

Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

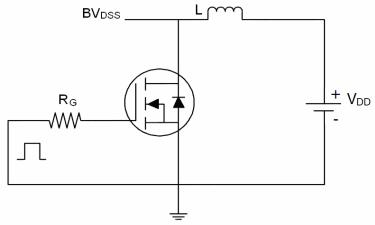
	Symbol	Parameter	Condition	Min	Тур	Max	Unit
Off Characteris	etics						
BV <sub>DSS</sub>	Drain-Source Breakd	Drain-Source Breakdown Voltage		100	110	-	V
I <sub>DSS</sub>	Zero Gate Voltage D	Zero Gate Voltage Drain Current		-	-	1	μΑ
I <sub>GSS</sub>	Gate-Body Leakag	e Current	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteris	tics (Note 3)						
V <sub>GS(th)</sub>	Gate Threshold	Voltage	$V_{DS}=V_{GS},I_{D}=250\mu A$	2	3	4	V
R <sub>DS(ON)</sub>	Drain-Source On-State	e Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =40A	-	9.9	13	mΩ
<b>g</b> <sub>FS</sub>	Forward Transcon	ductance	V <sub>DS</sub> =50V,I <sub>D</sub> =40A	100	-	-	S
Dynamic Chara	acteristics (Note4)						
C <sub>lss</sub>	Input Capacita	ance	V 50V/V 0V	-	4800	-	PF
C <sub>oss</sub>	Output Capaci	tance	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz	-	340	-	PF
C <sub>rss</sub>	Reverse Transfer Capacitance		F=1.UIVID2	-	150	-	PF
Switching Cha	racteristics (Note 4)						
t <sub>d(on)</sub>	Turn-on Delay	Time		-	15	-	nS
t <sub>r</sub>	Turn-on Rise	Time	$V_{DD}$ =50 $V$ , $I_D$ =40 $A$	-	50	-	nS
$t_{d(off)}$	Turn-Off Delay	Time	$V_{GS}$ =10V, $R_{GEN}$ =2.5 $\Omega$	-	40	-	nS
t <sub>f</sub>	Turn-Off Fall	Time		-	55	-	nS
Qg	Total Gate Ch	arge	\/ -90\/   -404	-	85	-	nC
Q <sub>gs</sub>	Gate-Source C	harge	$V_{DS}=80V,I_{D}=40A,$ $V_{GS}=10V$	-	18	-	nC
$Q_{gd}$	Gate-Drain Ch	arge	VGS-10V	-	28	-	nC
Drain-Source D	Diode Characteristics						
V <sub>SD</sub>	Diode Forward Vol	age (Note 3)	V <sub>GS</sub> =0V,I <sub>S</sub> =40A	-	-	1.2	V
Is	Diode Forward Cur		-	-	-	57	Α
t <sub>rr</sub>	Reverse Recover	y Time	TJ = 25°C, IF = 40A	-	38	80	nS
Qrr	Reverse Recovery	Charge	di/dt = 100A/μs(Note3)	-	53	100	nC
t <sub>on</sub>	Forward Turn-Or	n Time	Intrinsic turn-on time is negligible (turn-on is dominated by		y LS+LD)		

#### Notes:

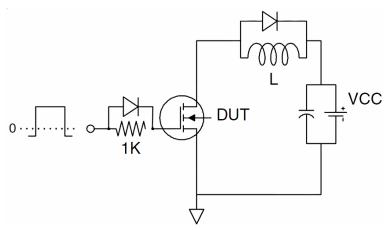
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition:Tj=25 $^{\circ}$ C,V<sub>DD</sub>=50V,V<sub>G</sub>=10V,L=0.5mH,Rg=25 $\Omega$

## **Test Circuit**

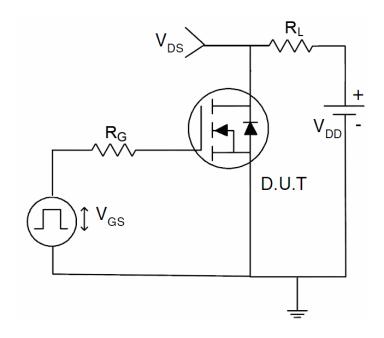
# 1) E<sub>AS</sub> test Circuit



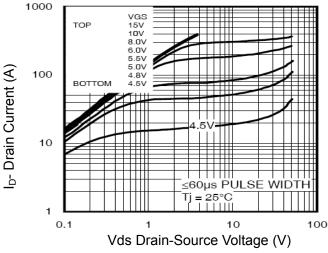
## 2) Gate charge test Circuit



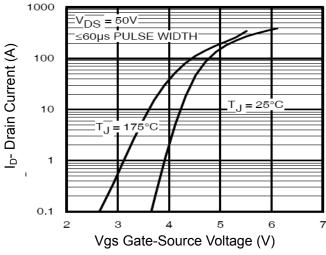
# 3) Switch Time Test Circuit



## **Typical Electrical and Thermal Characteristics (Curves)**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

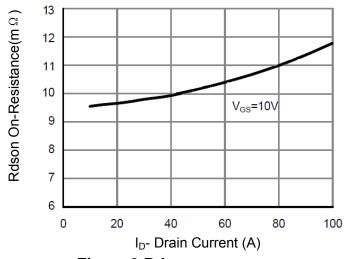


Figure 3 Rdson- Drain Current

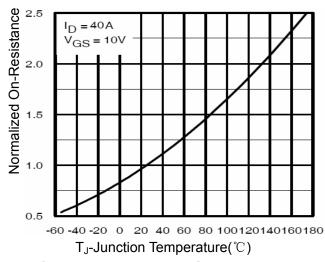


Figure 4 Rdson-JunctionTemperature

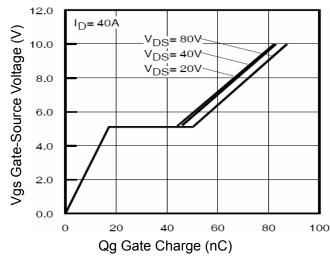


Figure 5 Gate Charge

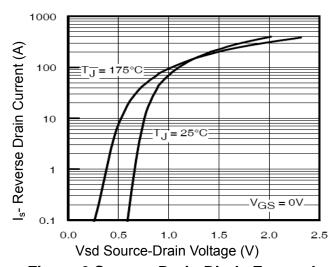


Figure 6 Source- Drain Diode Forward

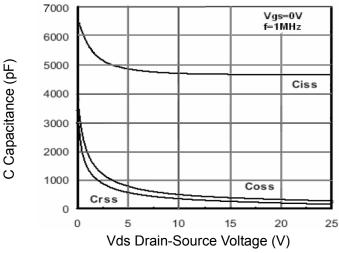


Figure 7 Capacitance vs Vds

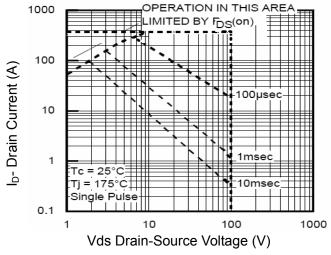


Figure 8 Safe Operation Area

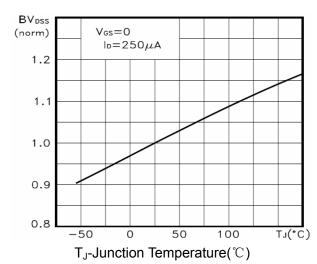


Figure 9 BV<sub>DSS</sub> vs Junction Temperature

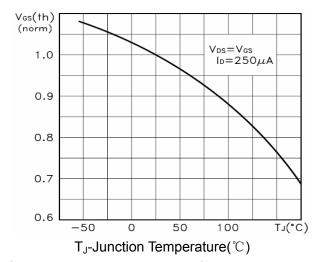


Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

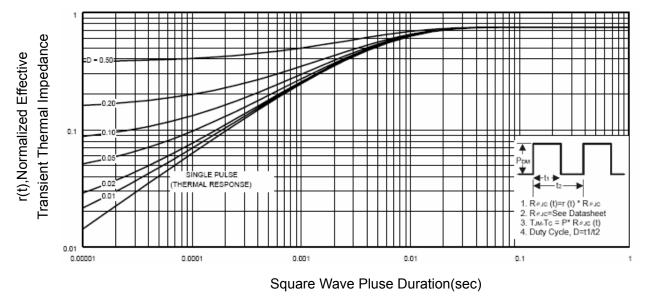
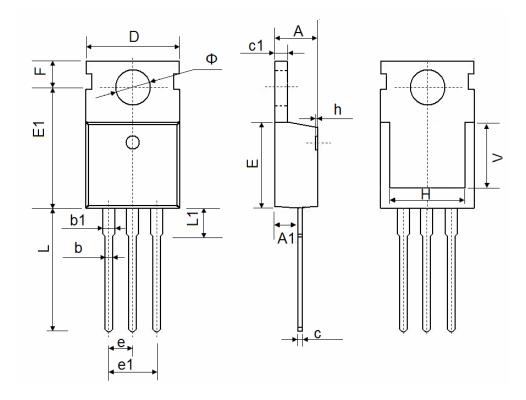


Figure 11 Normalized Maximum Transient Thermal Impedance

# **REASUNOS**

# **TO-220 Package Information**



Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
Е	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540	TYP.	0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500	7.500 REF.		REF.	
Ф	3.400	3.800	0.134	0.150	

# **REASUNOS**

#### **Attention**

- Any and all Reasunos products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your Reasunos representative nearest you before us ing any Reasunos products described or contained herein in such applications.
- Reasunos assumes no responsibility for equipment failu res that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Reasunos products described or contained herein.
- Specifications of any and all Reasunos products described or contained herein st ipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- Reasunos Semiconductor CO.,LTD. strives to supply hi gh-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all Reasunos products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of Reasunos Semiconductor CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. Reasunos believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the Reasunos product that you intend to use.
- This catalog provides information as of Mar.2015. Specifications and information herein are subject to change without notice.